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Substitute for form 1449APTO	Under the Peperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid CMS control number. Complete if Known		
INFORMATION DISCLOSURE	Application Number	09/945,535	
STATEMENT BY APPLICANT	Filing Date	August 30, 2001	
	First Named Inventor	Ahn, Kie	
FB 1 4 TOUTS &	Group Art Unit	2813	
\	Examiner Name	Blum, David	
Sheet 1 of 1	Attorney Docket No: 1	303.026US1	

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Index the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid CMB control number.

Complete If Known Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE **Application Number** 09/945535 **PATEMENT BY APPLICANT** August 30, 2001 Filing Date **First Named Inventor** Ahn, Kie **Group Art Unit** 2813 4 2005 FEB **Examiner Name** Blum, David Attorney Docket No: 1303.026US1 1 of 3

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(Use as many sheets as necessary)	Filing Date	August 30, 2001	
	First Named Inventor	Ahn, Kie	
YOL	Group Art Unit	2813	
COV	Examiner Name	Blum, David	
Sheet 2 of 3	Attorney Docket No: 1	303.026US1	

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Substitute for form 1449A/PTO	Complete if Known	required to respond to a collection of information unless it contains a valid CMS control number
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Application Number	09/945535
(Use as many sheets as necessary)	Filing Date	August 30, 2001
	First Named Inventor	Ahn, Kie
CO	Group Art Unit	2813
	Examiner Name	Blum, David
Sheet 3 of 3	Attorney Docket No: 1	303.026US1

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Approved for use through 07/31/2008, QMB 0651-0031
Patent & Tradement Office: U.S. DEPARTMENT OF CONDUCTION

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Approved for use through 10/31/2002, QUB 651-0031
Patent & Tredemark Office: U.S. DEPARTMENT OF COMMERCE

Substitute for form 1449A/PTO	Complete if Known	required to respond to a collection of information unless It contains a valid GMB control number
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Application Number	09/945535
(Use as many sheets as necessary)	Filing Date	August 30, 2001
	First Named Inventor	Ahn, Kie
	Group Art Unit	2813
	Examiner Name	Blum, David
Sheet 1 of 1	Attorney Docket No: 1	303.026US1

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Application Number	09/945,535
Filing Date	August 30, 2001
First Named Inventor	Ahn, Kie
Group Art Unit	2813
Examiner Name	Blum, David

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	Filing Date	August 30, 2001
STATEMENT BY APPLICANT (Use as many sheets as necessary) Fili Firs Gro Exa	First Named Inventor	Ahn, Kie
	Group Art Unit	2813
	Examiner Name	Blum, David
Sheet 2 of 4	Attorney Docket No: 1	303.026US1

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STATEMENT BY APPLICANT	Application Number	09/945,535
(Use as many sheets as necessary)	Filing Date	August 30, 2001
	First Named Inventor	Ahn, Kie
- OP	Group Art Unit	2813
COP	Examiner Name	Blum, David
Sheet 3 of 4	Attorney Docket No: 1	303.026US1

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	First Named Inventor	Ahn, Kie
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	Examiner Name	Blum, David .
Sheet 4 of 4	Attorney Docket No: 1	303.026US1

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Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid GMB control number Substitute for form 1449A/PTO Complete <u>if</u> Known INFORMATION DISCLOSURE 09/945535 **Application Number** STATEMENT BY APPLICANT (Use as many sheets as necessary) August 30, 2001 **Filing Date** First Named Inventor Ahn, Kie **Group Art Unit** 2813 Blum, David **Examiner Name** Attorney Docket No: 1303.026US1

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Application Number	09/945535	
	Filing Date	August 30, 2001	
707	First Named Inventor	Ahn, Kie	
COA	Group Art Unit	2813	
	Examiner Name	Blum, David	
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Complete if Known Substitute for form 1449A/PTO INFORMATION DISCLOSURE **Application Number** 09/945535 STATEMENT BY APPLICANT COPY (Use as many sheets as necessary) **Filing Date** August 30, 2001 **First Named Inventor** Ahn, Kie **Group Art Unit** 2813 **Examiner Name** Blum, David Attorney Docket No: 1303.026US1 Sheet 3 of 8

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